PSX-D

May 2011



PRODUCT DESCRIPTION

PSX-D provides the following product characteristics:

Technology	Phase Change Thermal Interface Material	
Appearance	Grey	
Phase change temperature	45 °C	
Product Benefits	 Reworkable Highly efficent thermal transfer Thixotropic above phase change temperature 	
Application Method	Stencil, Needle dispensed, Screen print or Manually apply	
Typical Assembly Applications	Microprocessors, GPUs, Multichip modules, ASICs, IGBT, FBDIMM/Memory, Lidded processor applications and Active heat sinks in electronic applications	
Application	Thermal management	
Substrate	None	

PSX-D is a reworkable and repeatable phase change thermal interface material suitable for use between a heat sink and a variety of heat dissipating components. This material offers the enhanced performance and reliability of a phase change thermal interface material with the application ease of thermal grease.

Shelf Life @ 25°C, months	≥6
Printed Material:	
Casson Base Viscosity @ 25 °C, mPa·s (cP):	
Haake 550, PK1, 1° :	
@ 1 rpm	100,000
@ 10 rpm	60,000
Specific Gravity	1.8
Solid Material:	
Specific Gravity	2.0
Thermal Conductivity, W/mK	3.4
Volumetric Expansion, %	15
TYPICAL DRYING PERFORMANCE	
Recommended Drying Conditions	
Thickness, mm	0.025
2 hours @ 22°C	

Thickness, mm 9 hours @ 22°C	0.102
Thickness, mm 5 hours @ 22°C	0.051
2 Hours @ 22 C	

Thickness, mm 24 hours @ 22°C

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

DIRECTIONS FOR USE

- 1. Once the compound is applied, it will dry to a solid phase change material. Drying is required for optimal thermal performance.
- 2. The material flows at the phase change temperature and conforms to the surface features of the heat sink and component.
- 3. Upon flow, air is expelled from the interface, reducing thermal impedance and the material performs as a highly efficient thermal transfer material.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: Below 27°C. Storage greater than 27°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Conversions

0.203

 $(^{\circ}C \ge 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in N/mm² x 145 = psi MPa x 145 = psi N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP



Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, Henkel Corporation and its affiliates ("Henkel") specifically disclaims all warranties expressed implied, or including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel products. Henkel specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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Reference 0.1